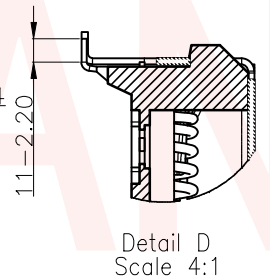
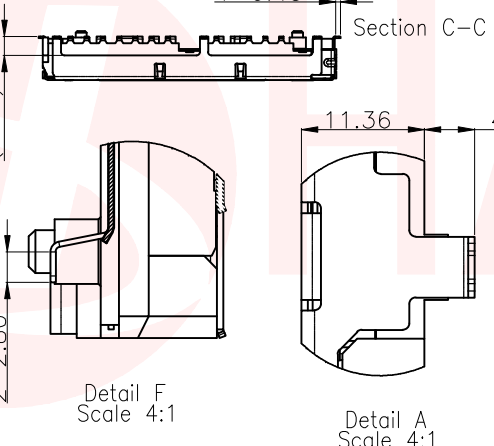
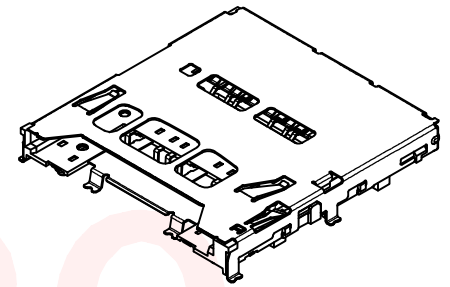
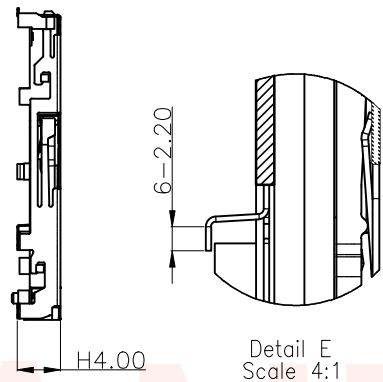
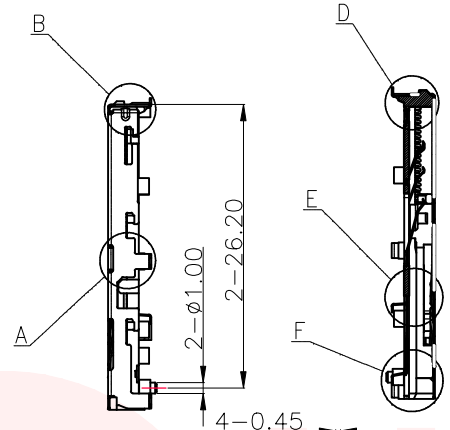
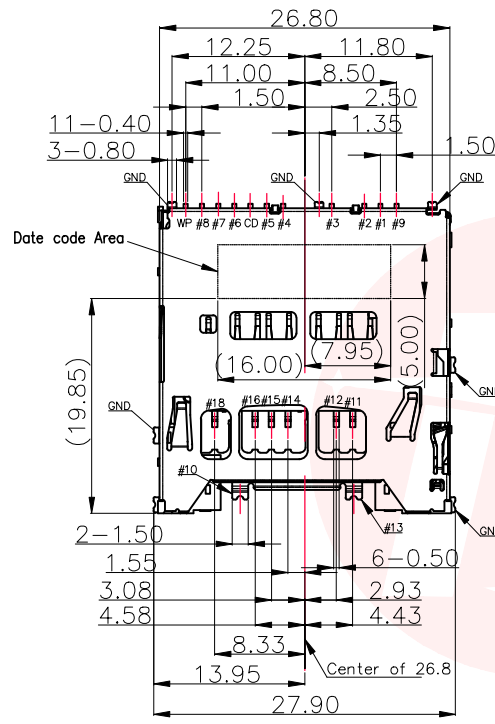
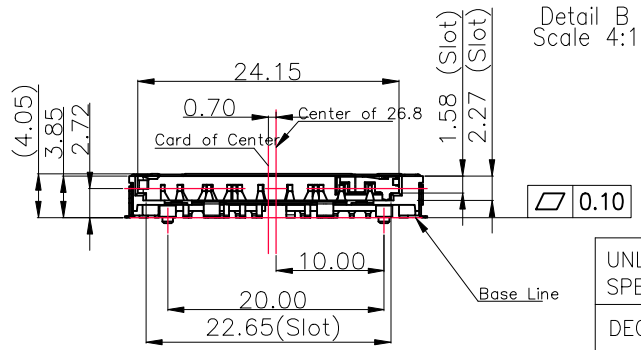
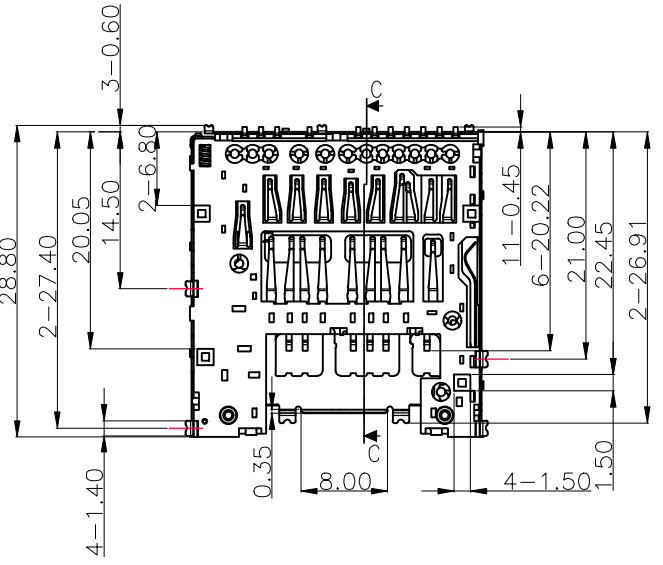




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



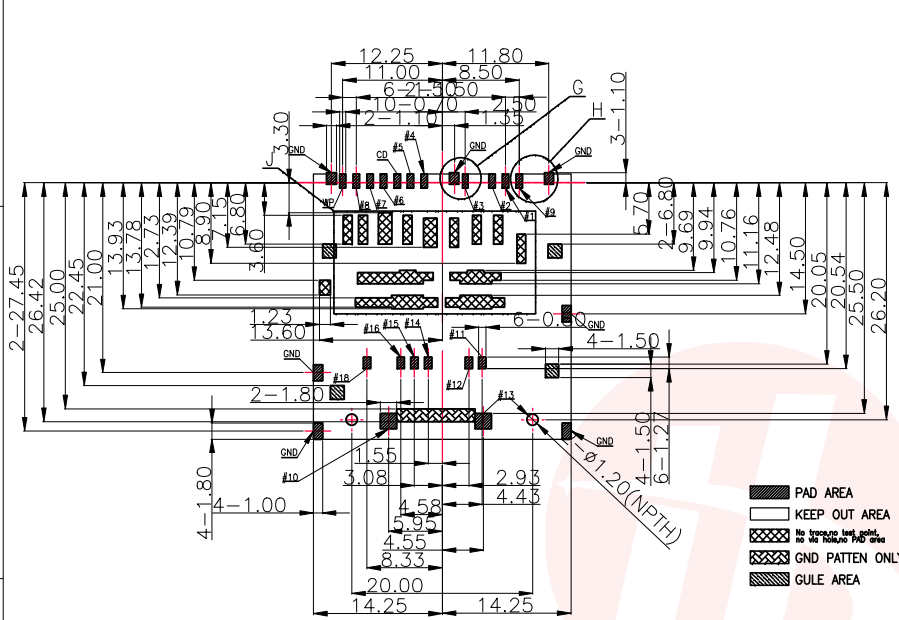
- Note:**
- Material:**
 - 1-1. Plastic: LCP, S475, Black, HF, UL94V-0
 - 1-2. Contact: C5210
 - 1-3. Shell: SUS304
 - Plating:**
 - 2-1. Contact:
 - Contact Area: Au 1μ" min. Plating Over Ni 50μ" min.
 - Soldertile: Gold Flash Plating Over Ni 50μ" min.
 - 2-2. Shell:
 - Solderable Ni 50μ" min. Over All
 - Contact And Soldertile Coplanarity to be 0.10mm max.**
 - Electrical Characteristics:**
 - 4-1. Contact Current Rating: 0.5Amperes.
 - 4-2. Dielectric Withstanding Voltage: AC500V r. m. s.
 - 4-3. Insulation Resistance: 1000 Megohms
 - 4-4. Contact Resistance: 100 Miliohms Maximum.
 - Environmental:**
 - 5-1. Operating Temperature: -25° C to +85° C.
 - 5-2. Salty spray: 48H



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS:	ANGLES:		
X : ±0.35	X : ±2°	TITLE	SD 7.0 H4.0 SMT PUSH-PUSH
X.X : ±0.20	X.X : ±1°	DWN	xiong
X.XX : ±0.10		PART NO.	SD-740
		CHKD	lee
		SCALE:	1:1
		UNIT:	mm
		APVD	wang
		SIZE:	A4
		SHEET:	10F 1
		REV:	A4
CUSTOMER COPY			

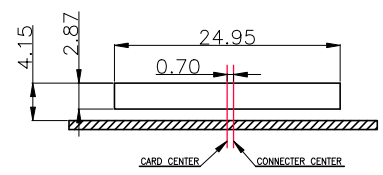


REV.	ECN NO OR DESCRIPTION	REVISED	DATE

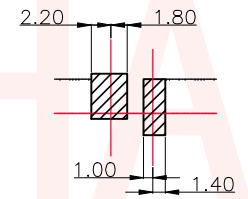


RECOMMENDED PCB LAYOUT (TOP VIEW)
TOLERANCE UNLESS OTHERWISE SPEC ± 0.05

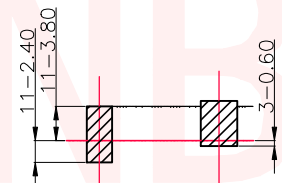
- PAD AREA
- KEEP OUT AREA
- No through hole pads, no via holes, no PAD areas
- GND PATTEN ONLY
- CULE AREA



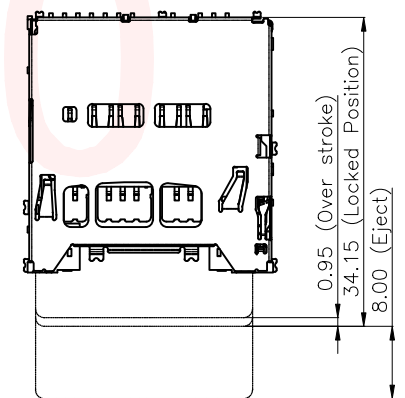
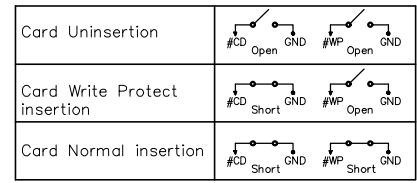
RECOMMENDED ID DIMENSION



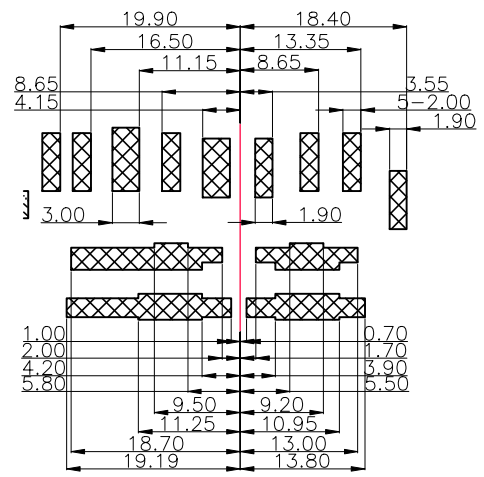
DETAIL G
SCALE 4:1



DETAIL H
SCALE 4:1



Card Push State



DETAIL J
SCALE 2:1

Pin Assignment

Pin#	SD Mode	UHS II Mode	SD Express Card	Pin#	SD Mode	UHS II Mode	SD Express Card
#1	CD/DAT3		PERST#	#11		D0+	PCle_Tx+
#2	CMD			#12		D0-	PCle_Tx-
#3	VSS1	VSS1	VSS1	#13		VSS4	VSS4
#4	VDD	VDD1	VDD1	#14		VDD2	VDD2
#5	CLK			#15		D1-	PCle_Rx-
#6	VSS2	VSS2	VSS2	#16		D1+	PCle_Rx+
#7	DAT0	RCLK+	REFCLK+	#17		VSS5	VSS5
#8	DAT1	RCLK-	REFCLK-	#18			VDD3
#9	DAT2		CLKREQ#	CD			Card Detect
#10		VSS3	VSS3	WP			Write Protect

Function #10, #13, #17 were integrated into 2 pin inMechanical design, and compares to the Layout would be (#10, #13)

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD		
DECIMALS:	ANGLES:	TITLE	SD 7.0 H4.0 SMT PUSH PUSH	
X ± 0.35	X $\pm 2^\circ$	DWN	xiong	PART NO. SD-740
X.X ± 0.20	X.X $\pm 1^\circ$	CHKD	lee	SCALE:1:1 UNIT: mm
X.XX ± 0.10		APVD	wang	SIZE: A4 SHEET:1OF 1
		REV: A4		
CUSTOMER COPY				

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[H1.37](#) [MICRO SIM 7P H1.35](#) [TF-CARD H1.8 SY](#) [MICRO SIM 6P H1.35](#) [TF-CARD H1.8](#) [TF-115Y-BCP9](#) [TF-115YY-ACP9](#) [SMN-309-](#)
[ARP6](#) [TF-115Y-ACP9](#) [TF-108-ARP10](#) [SMN-303S-ACP7](#) [SNO-14100](#) [SD-112S](#) [MUP-C7804-1](#) [KH-TF-07DT](#)